#### 502097770 10/17/2012

### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Yuan Dai	10/11/2012
Siew Sim-Tang	10/12/2012
Kamini Jagtiani	10/11/2012
Yang Sun	10/11/2012
Gangavara Prasad Varakur	10/11/2012
Bai Yang	10/11/2012

### **RECEIVING PARTY DATA**

Name:	FutureWei Technologies, Inc.		
Street Address:	5340 Legacy Drive		
Internal Address:	Suite 175		
City:	Plano		
State/Country:	TEXAS		
Postal Code:	75024		

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13653308

### **CORRESPONDENCE DATA**

Fax Number: 9727329218

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: (972)732-1001

Email: docketing@slater-matsil.com

Correspondent Name: Slater & Matsil, L.L.P. 17950 Preston Road Address Line 1:

Suite 1000 Address Line 2:

502097770

Address Line 4: Dallas, TEXAS 75252

ATTORNEY DOCKET NUMBER: HW 83546892US01

> **PATENT** REEL: 029145 FRAME: 0232

NAME OF SUBMITTER:	Sherry L. Colgrove
Total Attachments: 3 source=HW83546892US01_Assignment#pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignment#Pasource=HW83546892US01_Assignme	age2.tif

PATENT REEL: 029145 FRAME: 0233

### **ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, FutureWei Technologies, Inc. ("FutureWei"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said FutureWei, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said FutureWei, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to FutureWei, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said FutureWei, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said FutureWei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	System and Method for Flexible Distributed Massively Parallel Processing (MPP)			
SIGNATURE OF INVENTOR AND NAME	Yuan Dai	Siew Sim-Tang	Kal-Jaghani Kamini Jagtiani	Yang Sun
DATE	10/11/2012		10/11/2012	12/11/2012
RESIDENCE (City, State)	Cupertino, CA	Saratoga, CA	Sunnyvale, CA	Palo Alto, CA

ATTORNEY DOCKET NO. HW 83546892US01

#### **ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, FutureWei Technologies, Inc. ("FutureWei"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said FutureWei, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said FutureWei, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to FutureWei, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said FutureWei, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said FutureWei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	System and Method for Flexible Distributed Massively Parallel Processing (MPP)			
SIGNATURE OF INVENTOR AND NAME	Yuan Dai	Siew Sim-Tang	Kamini Jagtiani	Yang Sun
DATE		10-12-2012		
RESIDENCE (City, State)	Cupertino, CA	Saratoga, CA	Sunnyvale, CA	Palo Alto, CA

#### **ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, said application having been executed on the date set forth below; and

WHEREAS, FutureWei Technologies, Inc. (, a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said FutureWei, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said FutureWei, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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I hereby further agree that I will communicate to said FutureWei, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said FutureWei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	System and Method for Flexible Distributed Massively Parallel Processing (MPP)			
SIGNATURE OF INVENTOR	vou()	Pailas		· · · · · · · · · · · · · · · · · · ·
AND NAME	Gangavara Prasad Varakur	Bai Yang		
DATE	10/11/2012	10/11/2212		
RESIDENCE (City, State)	Danville, CA	Cupertino, CA		

Page 2 of 2

Assignment

PATENT REEL: 029145 FRAME: 0236